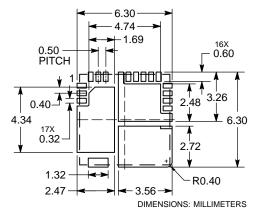


RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DATE 27 SEP 2017

NOTES:

- DIMENSIONING AND TOLERANCING PER
 ASME Y14.5M. 1994.
- A SME Y14.5M, 1994.

 2. CONTROLLING DIMENSIONS: MILLIMETERS.

 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM THE TERMINAL TIP.

 4. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.80	1.00	
A1		0.05	
A3	0.20	REF	
b	0.18	0.30	
b1	0.26	0.38	
D	6.00 BSC		
D2	3.12	3.32	
D3	2.47	2.57	
D4	2.13	2.33	
D5	1.47	1.58	
Е	6.00 BSC		
E2	4.04	4.14	
E3	2.25	2.35	
E4	2.35	2.55	
е	0.50 BSC		
L	0.30	0.50	
L3	0.10	0.30	
L4	0.70	0.90	

GENERIC MARKING DIAGRAM*



= Assembly Location

WL = Wafer Lot

YY = Year

WW = Work Week

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •' may or may not be present. Some products may not follow the Generic Marking.

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Α	UPDATED RECOMMENDED MOUNTING FOOTPRINT. REQ. BY R. SANTOS.	27 SEP 2017

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